SERIAL PRESENCE DETECT

M393B1K70DH0-CF808/CH908/CMA08/CK008

Organization: 1G x 72
Composition: 512M x 4 * 36ea
Used component part #: K4B2G0446D-HCF8/HCH9/HCK0/HCMA
of rows in module: 2 Row
of banks in component: 8 Banks
Feature: 30mm height & double sided component
Refresh: 8K/64ms
Bin Sort: F8(DDR3 1066@CL=7), H9(DDR3 1333@CL=9), K0(DDR3 1600@CL=11), MA(DDR3 1866@CL=13)
RCD Vendor and Revision: IDT A1(evergreen)

| Byte | Function Described | Function Supported | | | | Hex Value | | | | Note |
|------|---|---|-------------|-------------------------------|---------------------------|-----------|-------|-------|-------|------|
| # | | CF808 | CH908 | CMA08 | CK008 | CF808 | CH908 | CMA08 | CK008 | Note |
| 0 | Number of Serial PD Bytes Written / SPD Device Size / CRC Coverage | CRC coverage 0~116Byte, SPD Byte Total :256Byte, SPD Byte Use : 176Byte | | | | | 92 | ?h | | |
| 1 | SPD Revision | Version 1.1 | | | | | 11 | h | | |
| 2 | Key Byte / DRAM Device Type | | DDR3 S | SDRAM | | | OE | 3h | | |
| 3 | Key Byte / Module Type | | Register | ed DIMM | | | 01 | h | | |
| 4 | SDRAM Density and Banks | | 2Gb 8 | banks | | 03h | | | | |
| 5 | SDRAM Addressing | - 1 | Row : 15, C | Column : 11 | | 1Ah | | | | |
| 6 | Module Nominal Voltage, VDD | | 1.5V | only | | 00h | | | | |
| 7 | Module Organization | | 2Ran | k / x4 | | 08h | | | | |
| 8 | Module Memory Bus Width | | ECC, | 64bit | | | 0E | Bh | | |
| 9 | Fine Timebase Dividend and Divisor | | 1 | os | | | 11 | h | | |
| 10 | Medium Timebase Dividend | | 1/8 (0. | 125ns) | | 01h | | | | |
| 11 | Medium Timebase Divisor | 1/8 (0.125ns) | | | | 08h | | | | |
| 12 | SDRAM Minimum Cycle Time (tCKmin) | 1.875ns | 1.5ns | 1.071ns | 1.25ns | 0Fh | 0Ch | 09h | 0Ah | |
| 13 | Reserved | Reserved | | | | 00h | | | | |
| 14 | CAS Latencies Supported, Least Significant Byte | 6, 7, 8 | 6, 7, 8, | 6, 7, 8, 9 , 10, 11, 13 | 6, 7, 8, 9 , 10, 11 | 1Ch | 3Ch | FCh | FCh | |
| 15 | CAS Latencies Supported, Most Significant Byte | 6, 7, 8 | 6, 7, 8, | 6, 7, 8, 9 , 10, 11, 13 | 6, 7, 8, 9 , 10, 11 | 00h | 00h | 02h | 00h | |
| 16 | Minimum CAS Latency Time(tAAmin) | | 13.1 | 25ns | | 69h | | | | |
| 17 | Minimum Write Recovery Time (tWRmin) | | 15 | ns | | 78h | | | | |
| 18 | Minimum RAS# to CAS# Delay Time (tRCDmin) | | 13.1 | 25ns | | 69h | | | | |
| 19 | Minimum Row Active to Row Active Delay Time (tRRDmin) | 7.5ns | 6ns | 5ns | 6ns | 3Ch | 30h | 28h | 30h | |
| 20 | Minimum Row Precharge Time (tRPmin) | | 13.1 | 25ns | | 69h | | | | |
| 21 | Upper Nibbles for tRAS and tRC | - | | | | 11h | | | | |
| 22 | Minimum Active to Precharge Time (tRASmin), Least Significant Byte | 37.5ns | 36ns | 34ns | 35ns | 2Ch | 20h | 10h | 18h | |
| 23 | Minimum Active to Active/Refresh Time (tRCmin), Least Significatn Byte | 50.625ns | 49.125ns | 47.125ns | 48.125ns | 95h | 89h | 79h | 81h | |
| 24 | Minimum Refresh Recovery Time (tRFCmin), Least Significant Byte | | 160 |)ns | | 00h | | | | |
| 25 | Minimum Refresh Recovery Time (tRFCmin), Most Significant Byte | | 160 |)ns | | 05h | | | | |
| 26 | Minimum Internal Write to Read Command Delay Time (tWTRmin) | 7.5ns | | | | 3Ch | | | | |
| 27 | Minimum Internal Read to Precharge Command Delay Time (tRTPmin) | 7.5ns | | | | 3Ch | | | | |
| 28 | Upper Nibble for tFAW | 37.5ns | 30ns | 27ns | 30ns | 01h | 00h | 00h | 00h | |
| 29 | Minimum Four Activate WIndow Delay Time (tFAWmin), Least Significant Byte | 37.5ns | 30ns | 27ns | 30ns | 2Ch | F0h | D8h | F0h | |
| 30 | SDRAM Output Drivers supported | DLL off Mode, RZQ/6, RZQ/7 | | | | 83h | | | | |
| 31 | SDRAM Thermal and Refresh Options | No ODTS, No ASR | | | | 01h | | | | |
| 32 | Module Thermal Sensor | with TS | | | | 80h | | | | - |
| 33 | SDRAM Device Type | Standard Monolithic DRAM Device | | | | 00h | | | | |
| 34 | Fine Offset for SDRAM Minimum Cycle Time(tCKmin) | 1.875ns | 1.5ns | 1.071ns | 1.25ns | 00h | 00h | CAh | 00h | |
| 35 | Fine Offset for Minimum CAS Latency Time(tAAmin) | 13.125ns | | | | 00h | | | | |



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| Byte | Function Described | Function Supported | | | | Hex Value | | | | N |
|---------|---|--------------------|-----------|-------------|----------|-----------|-------|-------|-------|------|
| # | | CF808 | CH908 | CMA08 | CK008 | CF808 | CH908 | CMA08 | CK008 | Note |
| 36 | Fine Offset for Minimum RAS# to CAS# Delay Time(tRCDmin) | 13.125ns | | | | 00 |)h | | | |
| 37 | Fine Offset for Minimum Row Precharge Delay Time(tRPmin) | 13.125ns | | | | 00 |)h | | | |
| 38 | Fine Offset for Minimum Active to Active/Refresh Delay Time(tRCmin) | 50.625ns | 49.125ns | 47.125ns | 48.125ns | | 00 |)h | | |
| 39~59 | Reserved, General Section | Reserved | | | | | 00 |)h | | |
| 60 | Module Nominal Height | 30mm | | | | | OF | ħ | | |
| 61 | Module Maximum Thickness | | Planar Do | uble sides | | | 11 | lh | | |
| 62 | Reference Raw Card Used | | R/C E | Ξ, 2.0 | | 44h | | | | |
| 63 | DIMM Module Attributes | 2 Rows | s of DRAM | / 1 Registe | er used | 09h | | | | |
| 64 | Heat Spreader Solution | | witho | ut HS | | | | | | |
| 65 | Register vendor ID code(LSB) | | ID | T | | | | | | |
| 66 | Register vendor ID code(MSB) | | ID | T | | | В | 3h | | |
| 67 | Register Revision Number | | IDT A1(e | vergreen) | | | 63 | 3h | | |
| 68 | Register Type | | SSTE | 32882 | | | 00 |)h | | |
| 69 | Register Control Word Functions(RC0/RC1) | | Def | ault | | | 00 |)h | | |
| 70 | Register Control Word Functions(RC2/RC3) | | R/0 | CE | | | 50 |)h | | |
| 71 | Register Control Word Functions(RC4/RC5) | | R/0 | CE | | | 55 | 5h | | |
| 72 | Register Control Word Functions(RC6/RC7) | Default | | | | | 00 |)h | | |
| 73 | Register Control Word Functions(RC8/RC9) | Default | | | | | 00 |)h | | |
| 74 | Register Control Word Function(RC10, RC11) | Default | | | | | 00 |)h | | |
| 75 | Register Control Word Function(RC12, RC13) | Default | | | | | | | | |
| 76 | Register Control Word Function(RC14, RC15) | Default | | | | 00h | | | | |
| 77~116 | Reserved | | | - | | | | | | |
| 117 | Module Manufacturer ID Code, Least Significant Byte | | Sam | sung | | | | | | |
| 118 | Module Manufacturer ID Code, Most Significant Byte | | Sam | sung | | | | | | |
| 119 | Module ID: Module Manufacturing Location | | Onyanç | g Korea | | 01h | | | | |
| 120 | Module ID: Module Manufacturing Date | | | - | | 00h | | | | |
| 121 | Module ID: Module Manufacturing Date | - | | | | 00h | | | | |
| 122~125 | Module ID : Module Serial Number | - | | | 00h | | | | | |
| 126 | Cyclical Redundancy Code | - | • | | | DBh | 99h | FEh | ADh | |
| 127 | Cyclical Redundancy Code | - | - | | | E9h | 40h | 97h | 9Fh | |
| 128 | Module Part Number | | N | Л | | | | | | |
| 129 | Module Part Number | | 3 | 3 | | | | | | |
| 130 | Module Part Number | | Ş | 9 | | | | | | |
| 131 | Module Part Number | 3 | | | | | | | | |
| 132 | Module Part Number | В | | | | | | | | |
| 133 | Module Part Number | 1 | | | | | | | | |
| 134 | Module Part Number | К | | | | | | | | |
| 135 | Module Part Number | 7 | | | | | | | | |
| 136 | Module Part Number | 0 | | | | 30h | | | | |
| 137 | Module Part Number | D-die | | | | 44h | | | | |
| 138 | Module Part Number | Н | | | | 48h | | | | |
| 139 | Module Part Number | 0 | | | | 30h | | | | |
| 140 | Module Part Number | - | | | | 2Dh | | | | |
| 141 | Module Part Number | С | | | | 43h | | | | |
| 142 | Module Part Number | F | Н | М | K | 46h | 48h | 4Dh | 4Bh | |
| 143 | Module Part Number | 8 | 9 | Α | 0 | 38h | 39h | 41h | 30h | |



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| Byte # | Function Described | Function Supported | | | | Hex Value | | | | Note |
|-----------|------------------------------------|--------------------|-------|-------|-------|-----------|-------|-------|-------|------|
| | | CF808 | CH908 | CMA08 | CK008 | CF808 | CH908 | CMA08 | CK008 | |
| 144 | Module Part Number | Blank | | | | | | | | |
| 145 | Module Part Number | Blank | | | | | | | | |
| 146~147 | Module Revision Code | - | | | | | | | | |
| 148 | SDRAM Manufacturer's JEDEC ID Code | Samsung | | | | | | | | |
| 149 | SDRAM Manufacturer's JEDEC ID Code | Samsung | | | | | | | | |
| 150~175 | Manufacturer's Specific Data | - | | | | | | | | |
| 176~255 | Open for customer use | - | | | | | | | | |



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